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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Jack Deng
Chin Chen Kuo
Fu-Tien Weng
Chih-Kung Chang
Bii-Junq Chang

Execution Date(s) February 4, 2005

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Company, Ltd.

Internal Address: _____

Street Address: No. 8, Li-Hsin Road

6, Science-Based Industrial Park

City: Hsin-Chu

State: _____

Country: Taiwan, R.O.C. Zip: 300-77

Additional name(s) & address(es) attached? Yes No

113261 U.S. PTO
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3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: _____

Internal Address: _____

Street Address: 901 Main Street, Suite 3100

City: Dallas,

State: TX Zip: 75202-3789

Phone Number: 972-739-863

Fax Number: 214-200-0853

Email Address: ipdocketing@haynesbgoone.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

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9. Signature:

Signature

2-23-05

Date

David M. O'Dell, Reg. No. 42,044

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

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PATENT
REEL: 016321 FRAME: 0370

Docket No.: 2004-0783 / 24061.582
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | |
|-----|-----------------|----|
| (1) | Jack Deng | of |
| (2) | Chin Chen Kuo | of |
| (3) | Fu-Tien Weng | of |
| (4) | Chih-Kung Chang | of |
| (5) | Bii-Junq Chang | of |

have invented certain improvements in

ADVANCE RIDGE STRUCTURE FOR MICROLENS GAPLESS APPROACH

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on _____ and assigned application number _____; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Dated: 2/4 '05

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Inventor Signature

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Docket No.: 2004-0783 / 24061.582
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Bii-Junq Chang
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